



SOT1115

extremely thin small outline package; no leads; 6 terminals

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	XSON6
Package type industry code	XSON6
Package style descriptive code	XSON (extremely thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	7-4-2010

Table 1. Package summary

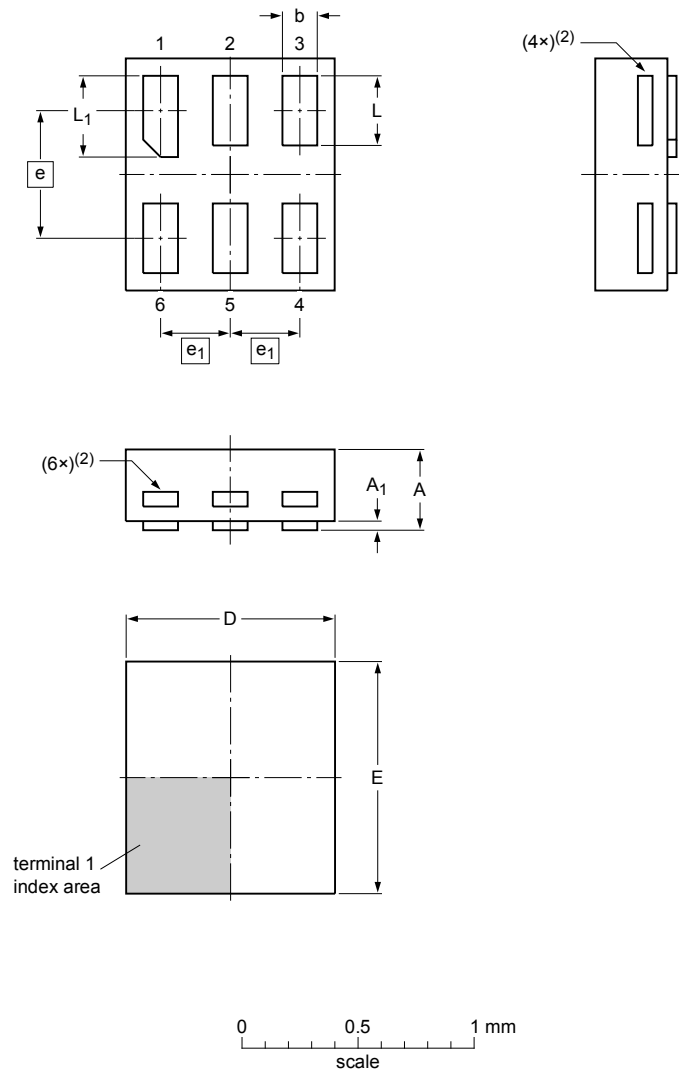
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.85	-	0.9	0.95	mm
E	package width	0.95	-	1	1.05	mm
A	seated height	[tbd]	-	[tbd]	0.35	mm
e	nominal pitch	-	-	0.55	-	mm
n ₂	actual quantity of termination	-	-	6	-	



2. Package outline

XSON6: extremely thin small outline package; no leads; 6 terminals; body 0.9 x 1.0 x 0.35 mm

SOT1115



Dimensions

Unit	A ⁽¹⁾	A ₁	b	D	E	e	e ₁	L	L ₁
mm	max 0.35	0.04	0.20	0.95	1.05			0.35	0.40
	nom		0.15	0.90	1.00	0.55	0.3	0.30	0.35
	min		0.12	0.85	0.95			0.27	0.32

Note

1. Including plating thickness.
2. Visible depending upon used manufacturing technology.

sot1115_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1115					10-04-02 10-04-07

Fig. 1. Package outline XSON6 (SOT1115)

3. Legal information

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